



Material Content Data Sheet



Sales Product Name		TLE94110EL		Issued		24. January 2018			
MA#		MA001653044							
Package		PG-SSOP-24-9		Weight*		150.84 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	3.240	2.15	2.15	21480	21480	
leadframe	inorganic material	phosphorus	7723-14-0	0.017	0.01		111		
	non noble metal	zinc	7440-66-6	0.067	0.04		446		
	non noble metal	iron	7439-89-6	1.345	0.89		8917		
wire	non noble metal	copper	7440-50-8	54.617	36.21	37.15	362087	371561	
	non noble metal	copper	7440-50-8	0.853	0.57	0.57	5657	5657	
	encapsulation	organic material	carbon black	1333-86-4	0.173	0.11		1148	
encapsulation	plastics	epoxy resin	-	7.965	5.28		52806		
	inorganic material	silicondioxide	60676-86-0	78.440	52.00	57.39	520025	573979	
leadfinish	non noble metal	tin	7440-31-5	2.911	1.93	1.93	19298	19298	
plating	noble metal	silver	7440-22-4	0.234	0.16	0.16	1553	1553	
glue	plastics	epoxy resin	-	0.244	0.16		1618		
	noble metal	silver	7440-22-4	0.732	0.49	0.65	4854	6472	
*deviation	< 10%				Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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